



Connectors > Socket Connectors > Pin Sockets > Miniature Spring Sockets: Open Bottom, Beryllium Copper, 5A



Socket Length: 3.51 mm [.138 in]

PCB Hole Diameter: 1.57 mm [.062 in]

Socket Sleeve Style: Open Bottom

Wire Size: 20 – 21 AWG

[All Miniature Spring Sockets: Open Bottom, Beryllium Copper, 5A \(5\)](#)

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Socket Sleeve Style	Open Bottom
Connector System	Cable-to-Board
Sealable	No

Configuration Features

Compatible With Wire & Cable Type	Discrete Wire
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Body Features

Sleeve Plating Material	Tin
Sleeve Material	Copper

Contact Features

Contact Spring Plating Material	Gold
Contact Base Material	Beryllium Copper
Contact Mating Area Plating Material Thickness	30 μm[30 μin]
Contact Spring Plating Thickness	.762 μm[30 μin]
Contact Current Rating (Max)	5 A

Termination Features

Termination Method to PCB	Through Hole - Press-Fit
Termination Method to Wire & Cable	Solder

Insertion Method	Hand/Semi-Automatic/Automatic
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Dimensions

PCB Thickness (Recommended)	.79 – 3.18 mm [.031 – .125 in]
Socket Length	3.51 mm [.138 in]
PCB Hole Diameter	1.57 mm [.062 in]
Wire Size	20 – 21 AWG
Mating Pin Diameter Range	.76 – .84 mm [.03 – .033 in]

Operation/Application

Solder Process Feature	None
Circuit Application	Power & Signal

Packaging Features

Packaging Method	Bag, Loose Piece
Packaging Quantity	2000

Other

Spring Material	Beryllium Copper
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

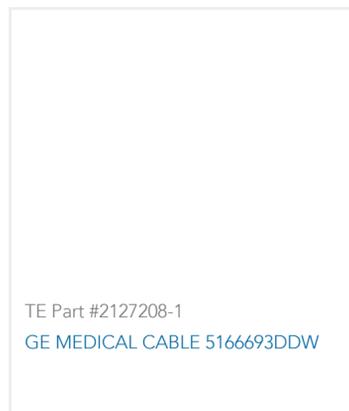
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Pin-in-Paste capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part

numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Customers Also Bought



Documents

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English

Customer View Model

[ENG_CVM_2-331677-2_AR1.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_2-331677-2_AR1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_2-331677-2_AR1.3d_stp.zip](#)



English

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[Product Specifications](#)

[Application Specification](#)

English